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Factory-direct manufacturer · Cleanroom production · Die-cut & laser conversion · Samples & quotation in 24 hours

PRODUCT DESCRIPTION

The **SD series** is the surface-tack grade of the WESTRU® PDMS gel film family — a cleanroom-produced, optically clear gel film used to hold, position and transfer small parts. The three grades are **distinguished by surface tack level** — T0 low, T4 medium, T6 high — so you can match the holding force to the part.

- Fully transparent — the held part stays visible and inspectable
- Elastic and resilient — holds repeatedly without permanent deformation
- Good dielectric performance — safe around sensitive devices
- Non-toxic, odourless and physiologically inert
- Stable over a wide temperature range — stays flexible when cold

FILM STRUCTURE

1 · Protective film layer	soft
2 · PDMS film layer	tacky, elastic
3 · Polyester substrate	rigid carrier
4 · Polyester substrate protective layer	soft

Protective films on both faces — keep them on until the moment of use, then peel them off to expose the tacky PDMS surface. The stated thickness is the PDMS film only and excludes the protective films.

SURFACE TACK GRADES & AVAILABILITY

Grade	Tack level	80 µm	200 µm	400 µm
T0	Low tack	✓	✓	✓
T4	Medium tack	✓	✓	✓
T6	High tack	—	✓	✓

Availability shown for standard production. Other thicknesses are made to order.

HOW TO JUDGE THE TACK LEVEL

- T0 — low tack:** no tack can be felt by hand; the film still clings to glass.
- T4 — medium tack:** tack can be felt by hand, but it is not pronounced.
- T6 — high tack:** tack is clearly noticeable by hand.

TYPICAL APPLICATIONS

- 2D material transfer** — pick up and release graphene, TMDC and other flakes
- Die & bare-die (KGD) positioning** — holds tiny parts still for inspection, sorting or processing
- Chip carrier film** — holding film for carrier plates, trays and jigs
- Chip packaging boxes** — liner that keeps devices fixed in transit
- Micro-component transfer printing** — micro-LED and similar small dies
- Wearable devices** — holds sensor modules and flexible patches in place
- Temporary wafer bonding & substrate holding** — dicing, back-grinding, handling
- Optics and precision parts** — transparent holding pads that stay inspectable
- Laboratory mounting** — temporary fixing of samples on slides and stages
- Electronics assembly** — staging pads for small parts during pick-and-place

THICKNESS, SIZE & ROLL

Stock thickness	80 / 200 / 400 µm — 200 and 400 µm in regular production
Other thicknesses	Made to order
Sheet size	200 × 150 mm (7.8 × 5.9 in) or 200 × 300 mm (7.8 × 11.8 in)
Roll	Standard width 300 mm; up to 500 mm custom
Conversion	Die-cutting and laser cutting to your drawing

HANDLING & STORAGE

Tack on both faces	Similar tack on both faces — there is no front or back to distinguish in use
Handling	Avoid touching the surface with fingers; keep the protective layer on until the moment of use
Thin films	Do not peel the film off the rigid carrier all at once — keep it on the carrier while handling, positioning and applying, then remove the carrier once the operation is finished. Once separated, thin film can self-adhere or curl like cling film and becomes hard to handle.
Storage	Room temperature, away from direct light, in the original packaging

Typical values, not guaranteed specifications. Tack level, thickness, dimensions and tolerances are made to order — tell us what you need to hold and we will recommend a grade and quote within 24 hours. A printed handling card ships with every order.